



# TRENTON SYSTEMS®

Engineered For Reliability

7<sup>th</sup> Gen

Core™ Processors

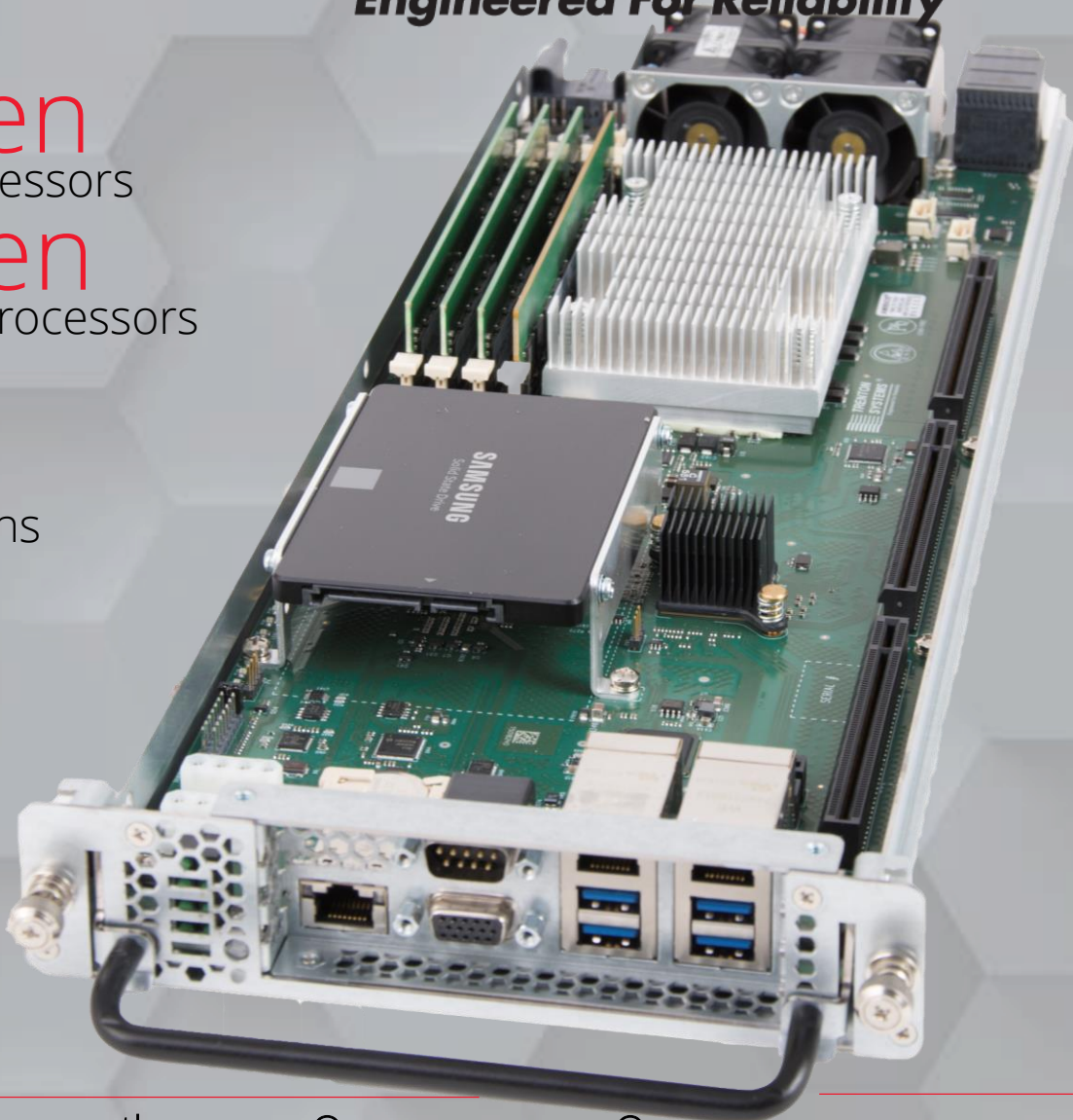
6<sup>th</sup> Gen

E3 Xeon® Processors

60°C

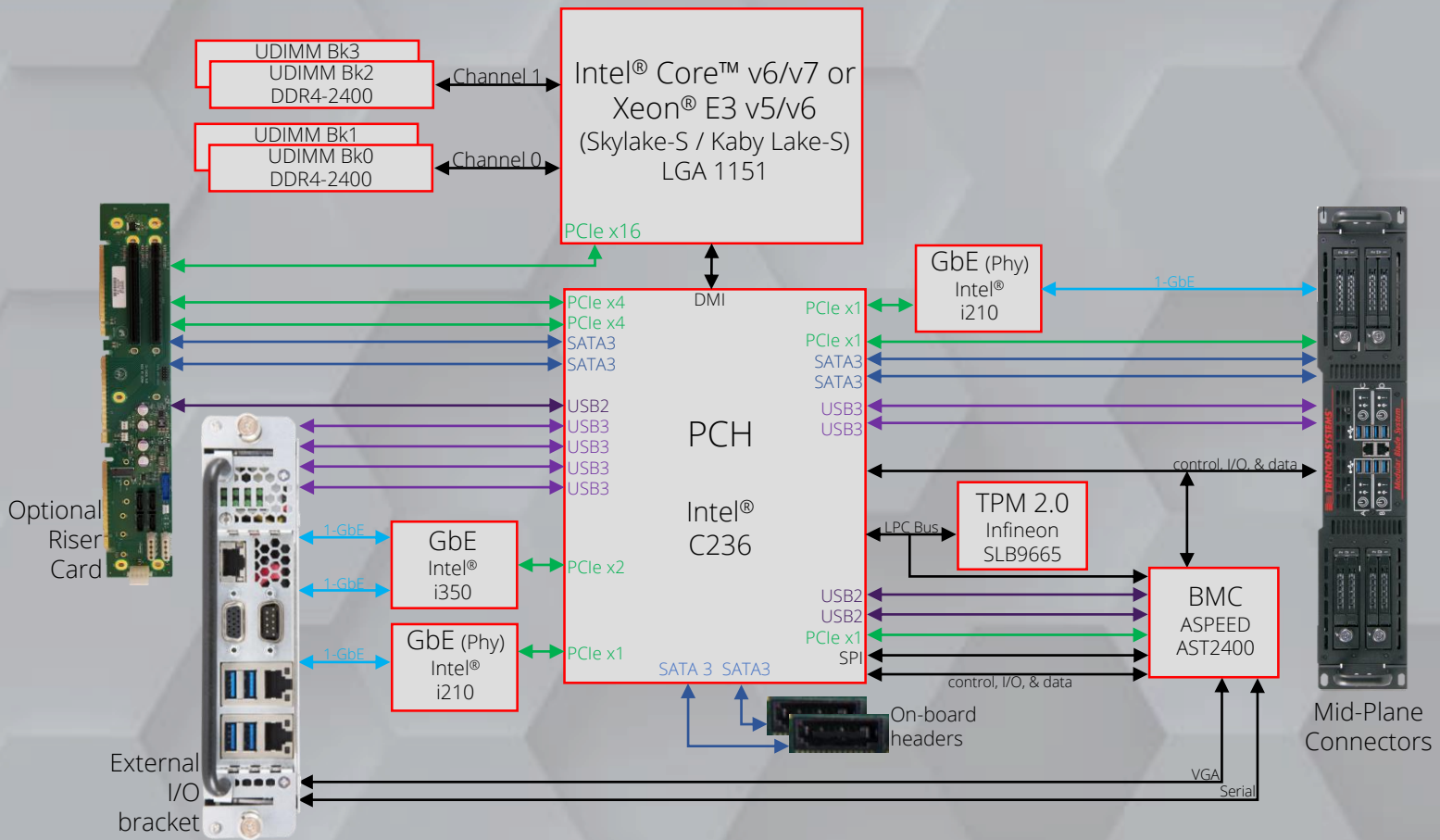
temp options

4.6 lbs  
weight



MBK8257

Processor	7 <sup>th</sup> Gen Intel® Core™ and Xeon® E3 v6 (Kaby Lake-S) 2.7GHz – 3.8GHz FCLGA1151 Socket
Memory	Four DDR4-2400 64GB max (4x16GB) ECC options available
Connections	Rear I/O: VGA, 3-1GbE (1 - IPMI), 4-USB3.0, serial Front: 2-USB3.0 Optional 4th 1GbE Port
Storage	Optional: 1-x16 PCIe Gen3, 1-x4 PCIe Gen3 Front: 2-SATA3.0 Onboard: 2-SATA3.0 Optional: 4-M.2



Processor Options:

Intel® CPU	Cores/ Hyper-Threading	CPU Speed	Mem Speed	ECC	Max Stress Temp
E3-1275 v6	4 / Yes	3.8GHz	DDR4-2400	Yes	40°C
Core i7-7700T	4 / Yes	2.9GHz	DDR4-2400	No	50°C
Core i5-7500T	4 / No	2.7GHz	DDR4-2400	No	50°C
Core i3-7101TE	2 / Yes	3.4GHz	DDR4-2400	Yes	50°C

More CPU Options: [www.TrentonSystems.com/processor-boards/mbk8257](http://www.TrentonSystems.com/processor-boards/mbk8257)

IPMI (System Management)
Intelligent Platform Management Interface (IPMI) v2.0 rev 1.1
Remote KVM, fan speed ctrl, voltage monitoring, fault sensing

Memory	
Two channel DDR4	
64GB max (4x16GB)	
ECC	
Optional Riser	
RCM40 8262 (2U height)	2-x16 gen 3 2-M.2 4-SATA3.0
RCM41 8277 (1U, butterfly)	2-x16 gen 3 2-SATA 3.0
RCM42 8269 (1U height)	4-M.2

Application Considerations	
Trusted Platform Module (TPM) 2.0	
RAID	0, 1, 5, 10
Storage Temp	-40° to 70°C
Humidity	5%-90% non-condensing
Agency Approvals	CE, UL, FCC



MBS2000  
19" depth  
Up to 4 segments  
1200W redundant P/S



MBS1002  
19" depth  
2 PCIe x16 slots  
2 SATA 3.0 hot swap  
1200W P/S

**100%** US Design & Assembly  
**27+** Years in Business  
**7+** Year Product Life Cycle  
**5** Year Warranty



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